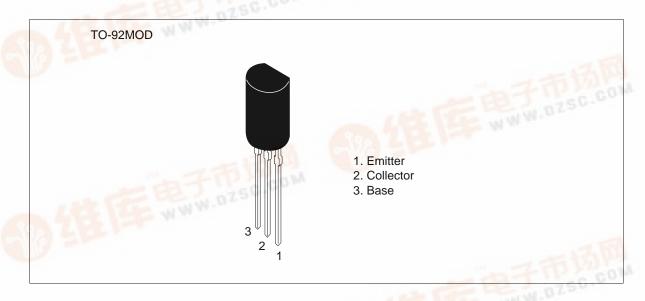
Silicon PNP Epitaxial

HITACHI

Application

- Low frequency high voltage amplifier
- Complementary pair with 2SD755, 2SD756 and 2SD756A

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

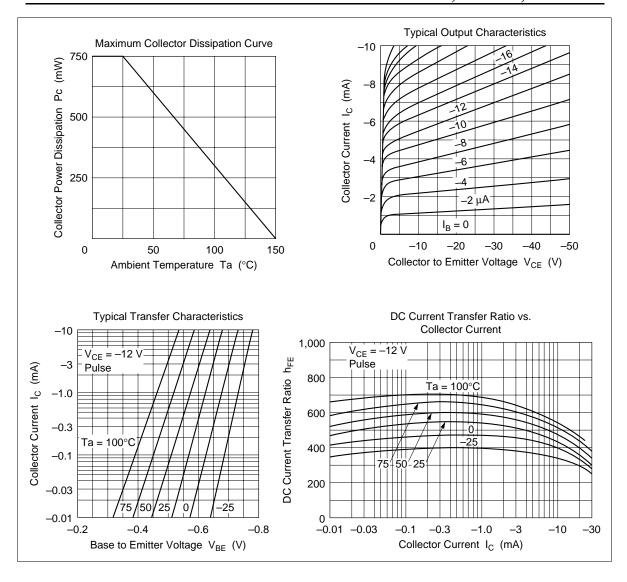
Item	Symbol	2SB715	2SB716	2SB716A	Unit
Collector to base voltage	V_{CBO}	-100	-120	-140	V
Collector to emitter voltage	V_{CEO}	-100	-120	-140	V
Emitter to base voltage	V_{EBO}	– 5	- 5	- 5	V
Collector current	I _c	– 50	– 50	- 50	mA
Collector power dissipation	P_{c}	750	750	750	mW
Junction temperature	Tj	150	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	-55 to +150	°C

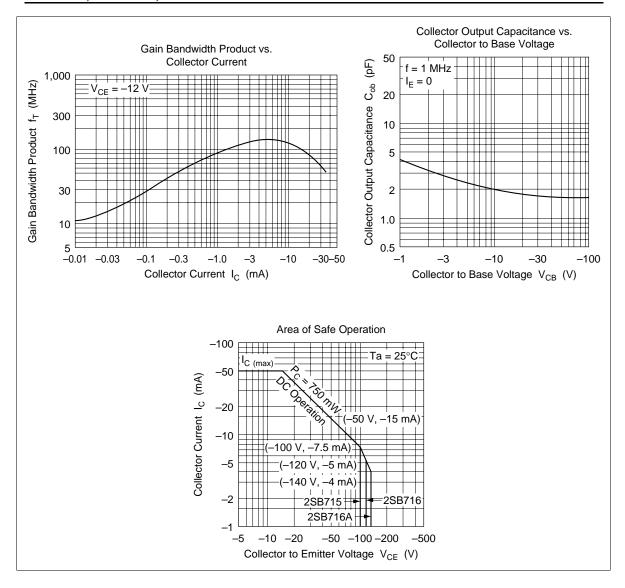
Electrical Characteristics ($Ta = 25^{\circ}C$)

		2SB7	15	2SB716		2SB716A						
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-100	_	_	-120	_	_	-140	_	_	V	$I_{C} = -10 \mu\text{A}, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-100	_	-	-120	_	-	-140	_	_	V	$I_C = -1 \text{ mA},$ $R_{BE} = \infty$
Collector cutoff current	I _{CBO}	_	_	-0.5	_	_	_	_	_	_	μΑ	$V_{CB} = -80 \text{ V}, I_{E} = 0$
		_	_	_	_	_	-0.5	_	_	-0.5	μΑ	$V_{CB} = -100 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE1} *1	250	_	800	250	_	800	250	_	500		$V_{CE} = -12 \text{ V},$ $I_{C} = -2 \text{ mA}$
	h _{FE2}	125	_	_	125	_	_	125	_	_		$V_{CE} = -12 \text{ V},$ $I_{C} = -10 \text{ mA}$
Base to emitter voltage	V _{BE}	_	_	-0.75	_	_	-0.75	_	_	-0.75	V	$V_{CE} = -12 \text{ V},$ $I_{C} = -2 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-0.2	_	_	-0.2	_	_	-0.2	V	$I_C = -10 \text{ mA},$ $I_B = -1 \text{ mA}$
Gain bandwidth product	f _T	_	150	_	_	150	-	_	150	_	MHz	$V_{CE} = -12 \text{ V},$ $I_{C} = -5 \text{ mA}$
Collector output capacitance	Cob	_	1.8	_	_	1.8	_	_	1.8	_	pF	$V_{CB} = -25 \text{ V}, I_{E} = 0,$ f = 1 MHz

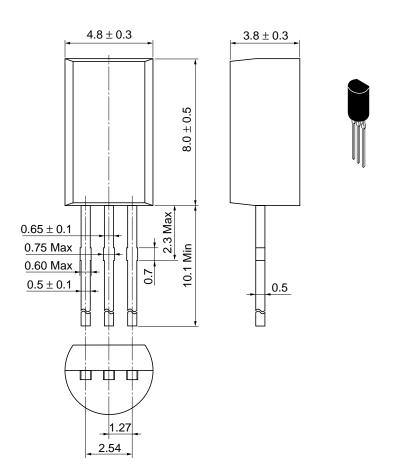
Note: 1. The 2SB715, 2SB716 and 2SB716A are grouped by h_{FE1} as follows.

	D	E
2SB715, 2SB716	250 to 500	400 to 800
2SB716A	250 to 500	_









Cautions

- 1. Hitachi neither warrants nor grants licenses of any rights of Hitachi's or any third party's patent, copyright, trademark, or other intellectual property rights for information contained in this document. Hitachi bears no responsibility for problems that may arise with third party's rights, including intellectual property rights, in connection with use of the information contained in this document.
- 2. Products and product specifications may be subject to change without notice. Confirm that you have received the latest product standards or specifications before final design, purchase or use.
- 3. Hitachi makes every attempt to ensure that its products are of high quality and reliability. However, contact Hitachi's sales office before using the product in an application that demands especially high quality and reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aeronautics, nuclear power, combustion control, transportation, traffic, safety equipment or medical equipment for life support.
- 4. Design your application so that the product is used within the ranges guaranteed by Hitachi particularly for maximum rating, operating supply voltage range, heat radiation characteristics, installation conditions and other characteristics. Hitachi bears no responsibility for failure or damage when used beyond the guaranteed ranges. Even within the guaranteed ranges, consider normally foreseeable failure rates or failure modes in semiconductor devices and employ systemic measures such as failsafes, so that the equipment incorporating Hitachi product does not cause bodily injury, fire or other consequential damage due to operation of the Hitachi product.
- 5. This product is not designed to be radiation resistant.
- 6. No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without written approval from Hitachi.
- 7. Contact Hitachi's sales office for any questions regarding this document or Hitachi semiconductor products.

HTACH

Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

NorthAmerica http:semiconductor.hitachi.com/

Europe Asia (Singapore) Asia (Taiwan) Asia (HongKong) http://www.hitachi-eu.com/hel/ecg http://www.has.hitachi.com.sg/grp3/sicd/index.htm http://www.hitachi.com.tw/E/Product/SICD_Frame.htm

http://www.hitachi.com.hk/eng/bo/grp3/index.htm

Japan http://www.hitachi.co.jp/Sicd/indx.htm

For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany

Tel: <49 > (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead

Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office

3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

Copyright ' Hitachi, Ltd., 1999. All rights reserved. Printed in Japan.